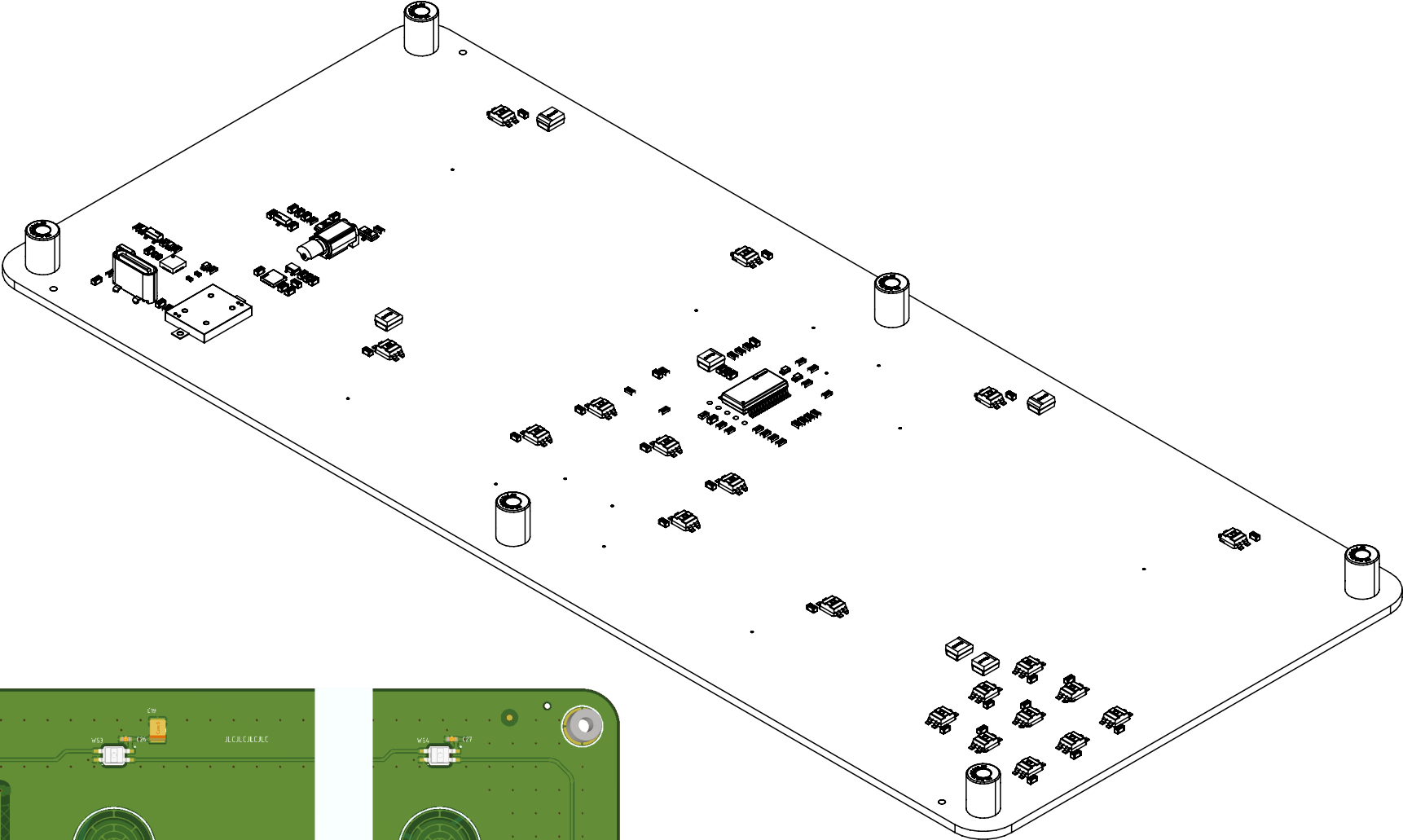


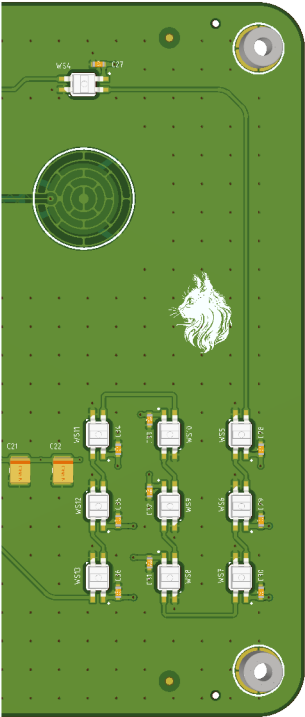
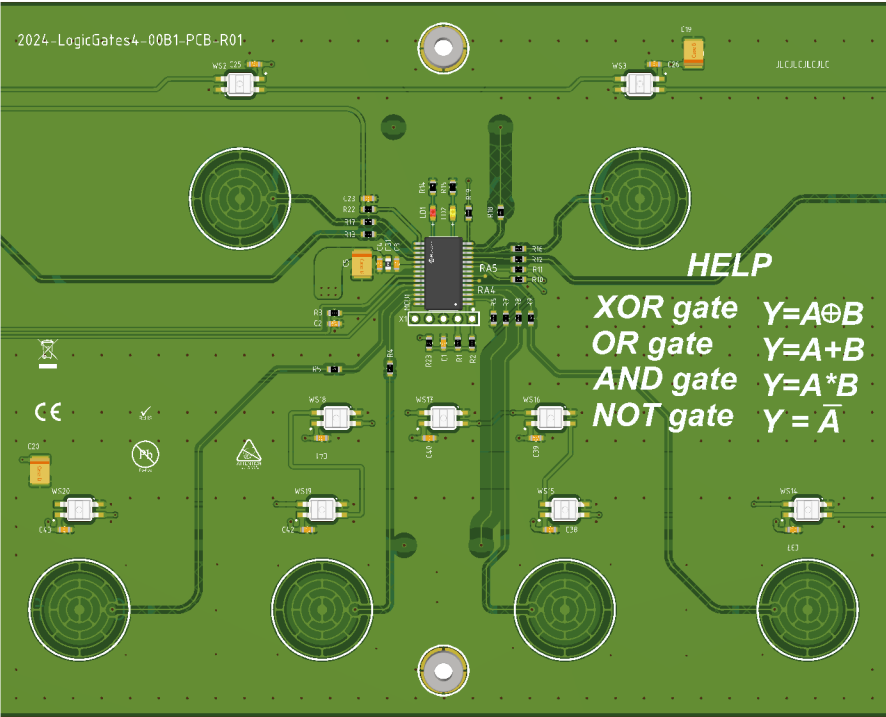
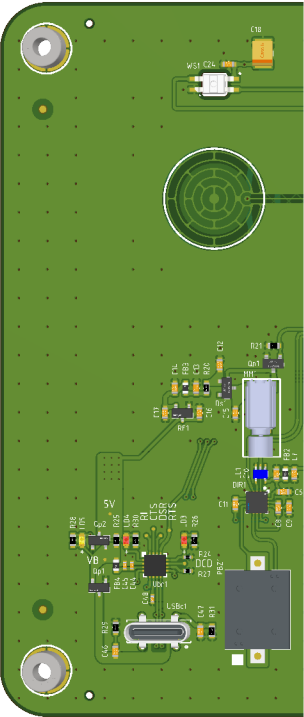


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View from Front side (Scale 1:1)










Realistic View





Layer Stack Legend

	Material	Layer	Thickness	Dielectric Material	Type	Gerber
		Top Overlay			Legend	GTO
	Surface Material	Top Solder	0.01mm	Solder Resist	Solder Mask	GTS
	Copper	Top Layer 1	0.04mm		Signal	GTL
	Core		1.51mm	FR-4 Standard Tg 130-140/ Tg 155	Dielectric	
	Copper	Bottom Layer 2	0.04mm		Signal	GBL
	Surface Material	Bottom Solder	0.01mm	Solder Resist	Solder Mask	GBS
		Bottom Overlay			Legend	GBO

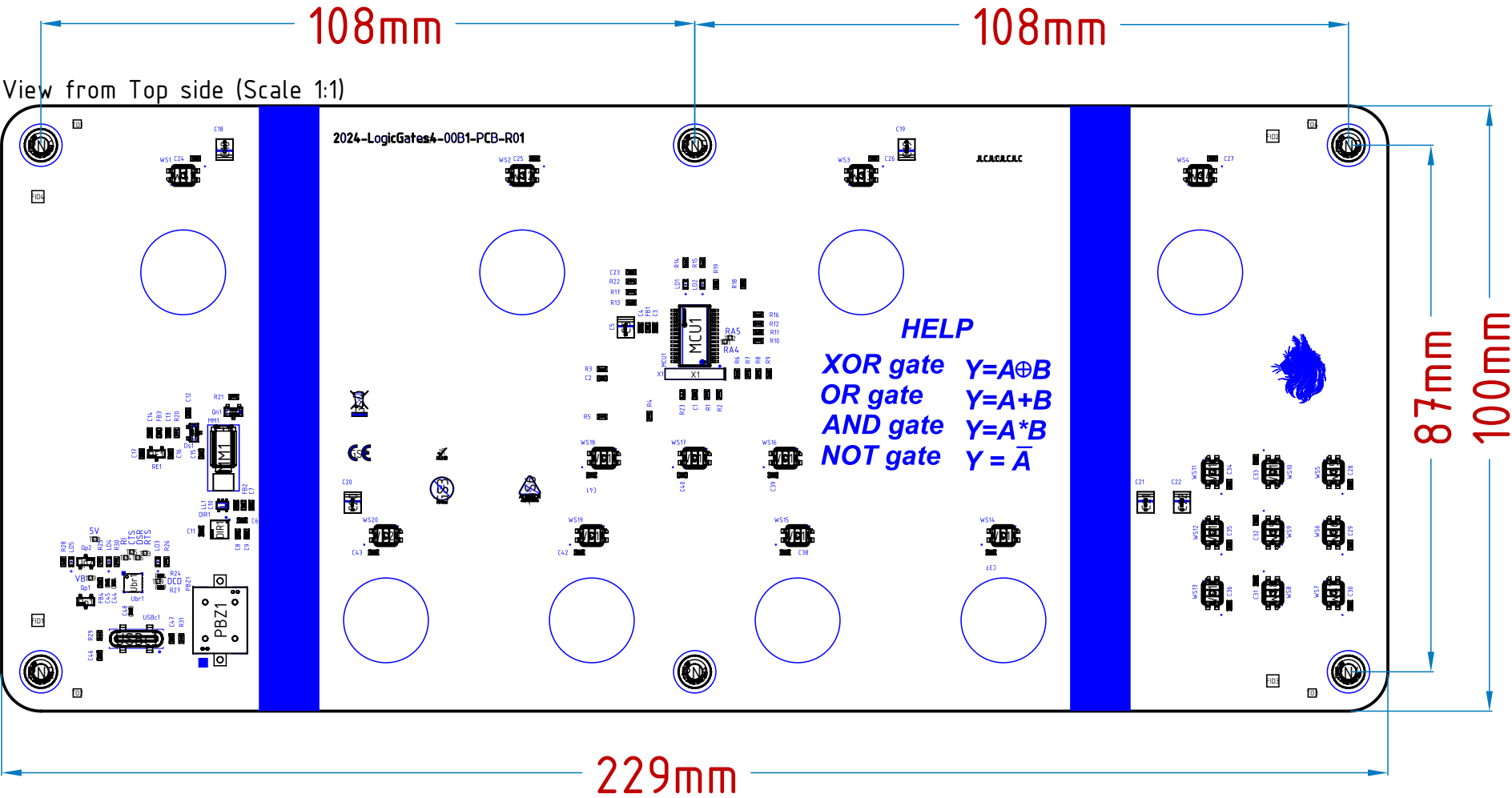
Drill Table					Total thickness: 1.60mm				
Symbol	Count	Hole Size	Plated	Hole Tolerance					
○	629	0.40	Plated						
□	5	0.80	Plated						
☆	1	0.65	Non-Plated						
⊠	4	0.70	Plated						
◇	1	0.65	Plated						
▽	4	1.15	Non-Plated						
✕	6	4.22	Non-Plated						
⊕	83	0.30	Plated						

Components:  
Number of Mixed Technology Components = 7  
Number of SMD Components = 132  
Number of Thru-Hole Components = 18

PCB:  
Number of Copper Layer = 2

Primitives:  
Number of Blind Via = 0  
Number of Buried Via = 0  
Number of Micro Via = 0  
Number of SMD Pads = 392  
Number of Thru-Hole = 34  
Number of Stacked Via = 0  
Number of Thru-Hole Vias = 699

FAB:  
Max Weight of Inner Copper Layers = None  
Max Weight of Outer Copper Layers = 1/8oz  
Min Hole Size = 0mm  
Number of Unique Hole Sizes = 8  
Bottom Color Soldier Mask Layer = No color  
Top Color Soldier Mask Layer = No color



View from Right side (Scale 1:1)

